

| Ref # | Hits | Search Query | DBs | Default Operator | Plurals | Time Stamp |
|-------|------|--|--------------------------------|------------------|---------|------------------|
| L15 | 2 | (29/610.1).ccls. and (thick adj resistor) and substrate and (passivation or mask or photomask or (dry adj film) or dielectric) | US-PGPUB; USPAT; IBM_TDB | OR | ON | 2005/10/28 08:06 |
| L30 | 27 | (29/825,829,846).ccls. and (resistor) and (circuit) and substrate and (passivation or mask or photomask or (dry adj film)) and titanium and copper and (electroplat\$3 or plat\$3) and (board) | US-PGPUB; USPAT; IBM_TDB | OR | ON | 2005/10/28 08:12 |
| L31 | 4 | (29/825,829,846).ccls. and (resistor) and (circuit) and substrate and ((passivation or mask or photomask or (dry adj film) or protection) adj layer) and titanium and copper and (electroplat\$3 or plat\$3) and (board) | US-PGPUB; USPAT; IBM_TDB | OR | ON | 2005/10/28 08:11 |
| L32 | 1 | (29/857,868,874).ccls. and (resistor) and (circuit) and substrate and ((passivation or mask or photomask or (dry adj film) or protection) adj layer) and titanium and copper and (electroplat\$3 or plat\$3) and (board) | US-PGPUB; USPAT; IBM_TDB | OR | ON | 2005/10/28 08:13 |
| L34 | 3 | (361/321.4).ccls. and (resistor) and (circuit) and substrate and (passivation or mask or photomask or (dry adj film)) and (electroplat\$3 or plat\$3) and (board) | US-PGPUB; USPAT; IBM_TDB | OR | ON | 2005/10/28 08:11 |
| L35 | 5 | (216/16,40).ccls. and (resistor) and (circuit) and substrate and (passivation or mask or photomask or (dry adj film)) and titanium and copper and (electroplat\$3 or plat\$3) and (board) | US-PGPUB; USPAT; IBM_TDB | OR | ON | 2005/10/28 08:13 |
| L36 | 35 | (174/255,260).ccls. and (resistor) and (circuit) and substrate and (passivation or mask or photomask or (dry adj film)) and titanium and copper and (electroplat\$3 or plat\$3) and (board) | US-PGPUB; USPAT; IBM_TDB | OR | ON | 2005/10/28 08:14 |

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| L37 | 15 | (174/255,260).ccls. and (resistor) and (circuit) and substrate and ((passivation or mask or photomask or (dry adj film) or protection) adj layer) and titanium and copper and (electroplat\$3 or plat\$3) and (board) | US-PGPUB; USPAT; IBM_TDB | OR | ON | 2005/10/28 08:15 |
| L39 | 1 | (438/745).ccls. and (resistor) and (circuit) and substrate and (passivation or mask or photomask or (dry adj film)) and titanium and copper and (electroplat\$3 or plat\$3) and (board) | US-PGPUB; USPAT; IBM_TDB | OR | ON | 2005/10/28 08:14 |
| L40 | 2 | (427/101).ccls. and (resistor) and (circuit) and substrate and ((passivation or mask or photomask or (dry adj film) or protection) adj layer) and titanium and copper and (electroplat\$3 or plat\$3) and (board) | US-PGPUB; USPAT; IBM_TDB | OR | ON | 2005/10/28 08:15 |
| S1 | 6 | (ru-shao-pin).in. | US-PGPUB; USPAT; IBM_TDB | OR | ON | 2005/10/25 13:56 |
| S2 | 0 | ("thickadjfilmadjresistor").PN. | US-PGPUB; USPAT; IBM_TDB | OR | OFF | 2005/10/25 13:56 |
| S3 | 1518 | thick adj film adj resistor | US-PGPUB; USPAT; IBM_TDB | OR | ON | 2005/10/25 13:57 |
| S4 | 17 | (thick adj film adj resistor) and (thin adj film adj circuit) | US-PGPUB; USPAT; IBM_TDB | OR | ON | 2005/10/25 14:00 |
| S5 | 1332 | (thick adj film adj resistor) and (circuit) | US-PGPUB; USPAT; IBM_TDB | OR | ON | 2005/10/25 14:00 |
| S6 | 249 | (thick adj film adj resistor) and (circuit) and substrate and (passivation or mask or photomask) | US-PGPUB; USPAT; IBM_TDB | OR | ON | 2005/10/25 14:01 |
| S7 | 260 | (thick adj film adj resistor) and (circuit) and substrate and (passivation or mask or photomask or (dry adj film)) | US-PGPUB; USPAT; IBM_TDB | OR | ON | 2005/10/25 14:01 |
| S8 | 66 | (thick adj film adj resistor) and (circuit) and substrate and (passivation or mask or photomask or (dry adj film)) and titanium | US-PGPUB; USPAT; IBM_TDB | OR | ON | 2005/10/25 14:02 |

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| S9 | 63 | (thick adj film adj resistor) and (circuit) and substrate and (passivation or mask or photomask or (dry adj film)) and titanium and copper | US-PGPUB; USPAT; IBM_TDB | OR | ON | 2005/10/25 14:02 |
| S10 | 52 | (thick adj film adj resistor) and (circuit) and substrate and (passivation or mask or photomask or (dry adj film)) and titanium and copper and expos\$3 | US-PGPUB; USPAT; IBM_TDB | OR | ON | 2005/10/25 14:02 |
| S11 | 40 | (thick adj film adj resistor) and (circuit) and substrate and (passivation or mask or photomask or (dry adj film)) and titanium and copper and expos\$3 and (electroplat\$3 or plat\$3) | US-PGPUB; USPAT; IBM_TDB | OR | ON | 2005/10/25 14:03 |
| S12 | 22 | (thick adj film adj resistor) and (circuit) and substrate and (passivation or mask or photomask or (dry adj film)) and titanium and copper and expos\$3 and (electroplat\$3 or plat\$3) and (board) | US-PGPUB; USPAT; IBM_TDB | OR | ON | 2005/10/28 08:02 |
| S13 | 1 | ("6507993").PN. | US-PGPUB; USPAT; IBM_TDB | OR | OFF | 2005/10/26 13:14 |
| S14 | 23 | (thick adj resistor) and circuit and electrode and substrate | US-PGPUB; USPAT; IBM_TDB | OR | ON | 2005/10/26 13:20 |
| S15 | 25 | (thick adj resistor) and electrode and substrate | US-PGPUB; USPAT; IBM_TDB | OR | ON | 2005/10/26 13:21 |
| S16 | 314956 | (thick adj resistor) and electrode and substrate (passivation or mask or photomask) | US-PGPUB; USPAT; IBM_TDB | OR | ON | 2005/10/26 13:21 |
| S17 | 9 | (thick adj resistor) and electrode and substrate and (passivation or mask or photomask) | US-PGPUB; USPAT; IBM_TDB | OR | ON | 2005/10/26 13:22 |
| S18 | 9 | (thick adj resistor) and electrode and substrate and (passivation or mask or photomask or (dry adj film)) | US-PGPUB; USPAT; IBM_TDB | OR | ON | 2005/10/26 13:22 |
| S19 | 4 | (thick adj resistor) and electrode and substrate and (passivation or mask or photomask or (dry adj film)) and (plat\$3 or electroplat\$3) | US-PGPUB; USPAT; IBM_TDB | OR | ON | 2005/10/26 13:26 |
| S20 | 7 | ("5379016").URPN. | USPAT | OR | ON | 2005/10/26 13:26 |

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| S21 | 2 | (thick adj resistor) and board and (circuit or wiring) and substrate and (passivation or mask or photomask or (dry adj film)) and (plat\$3 or electroplat\$3) | US-PGPUB; USPAT; IBM_TDB | OR | ON | 2005/10/26 13:28 |
| S22 | 1 | (thick adj resistor) and (printed adj (circuit or wiring) adj board) and (passivation or mask or photomask or (dry adj film)) and (plat\$3 or electroplat\$3) | US-PGPUB; USPAT; IBM_TDB | OR | ON | 2005/10/26 13:43 |
| S23 | 2 | ((("4892776") or ("5510594"))).PN. | US-PGPUB; USPAT; IBM_TDB | OR | OFF | 2005/10/26 13:31 |
| S24 | 29 | ("4892776").URPN. | USPAT | OR | ON | 2005/10/26 13:31 |
| S25 | 18 | ("2945180" "3808576" "3813631" "4174513" "4737747" "4888574" "4892776" "5336391" "5422313" "5483217" "5756971" "5864281" "5907273" "5994997" "6141870" "6232042" "6248612").PN. | US-PGPUB; USPAT; USOCR | OR | ON | 2005/10/26 13:34 |
| S26 | 11 | ("5994997").URPN. | USPAT | OR | ON | 2005/10/26 13:36 |
| S27 | 5 | ("4293839").URPN. | USPAT | OR | ON | 2005/10/26 13:40 |
| S28 | 5 | ("4293839").URPN. | USPAT | OR | ON | 2005/10/26 13:41 |
| S29 | 2 | (thick adj resistor) and (board) and (passivation or mask or photomask or (dry adj film)) and (plat\$3 or electroplat\$3) | US-PGPUB; USPAT; IBM_TDB | OR | ON | 2005/10/26 13:42 |
| S30 | 3318 | (resistor) and (printed adj (circuit or wiring) adj board) and (passivation or mask or photomask or (dry adj film)) and (plat\$3 or electroplat\$3) | US-PGPUB; USPAT; IBM_TDB | OR | ON | 2005/10/26 13:43 |
| S31 | 93 | ((embedd\$3 or integrat\$3) near resistor) and (printed adj (circuit or wiring) adj board) and (passivation or mask or photomask or (dry adj film)) and (plat\$3 or electroplat\$3) | US-PGPUB; USPAT; IBM_TDB | OR | ON | 2005/10/26 13:43 |
| S32 | 28 | ((embedd\$3 or integrat\$3) near resistor) same (printed adj (circuit or wiring) adj board) and (passivation or mask or photomask or (dry adj film)) and (plat\$3 or electroplat\$3) | US-PGPUB; USPAT; IBM_TDB | OR | ON | 2005/10/26 13:43 |
| S33 | 15 | (takata-eiichi).in. | US-PGPUB; USPAT; IBM_TDB | OR | ON | 2005/10/26 14:00 |

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| S34 | 31 | (alpha adj tungsten) and tungsten | US-PGPUB; USPAT; IBM_TDB | OR | ON | 2005/10/26 14:01 |
| S35 | 11 | ("5994997").URPN. | USPAT | OR | ON | 2005/10/27 07:06 |
| S36 | 1419 | ((titanium near copper) with (layer or film or coating)) | USPAT | OR | ON | 2005/10/27 07:07 |
| S37 | 184 | ((titanium near copper) near (layer or film or coating)) | USPAT | OR | ON | 2005/10/27 07:07 |
| S38 | 4 | ((((titanium near copper) near (layer or film or coating)) with (terminal or electrode)) and (resistor or resistive or resistance) | USPAT | OR | ON | 2005/10/27 07:08 |
| S39 | 26711 | (motor or stator or rotor) and winding and slot | US-PGPUB; USPAT; IBM_TDB | OR | ON | 2005/10/27 08:05 |
| S40 | 7240 | (motor or stator or rotor) and (winding with slot) | US-PGPUB; USPAT; IBM_TDB | OR | ON | 2005/10/27 08:05 |
| S41 | 2427 | (motor or stator or rotor) and (winding with slot) and stack\$3 | US-PGPUB; USPAT; IBM_TDB | OR | ON | 2005/10/27 08:06 |
| S42 | 1228 | (motor or stator or rotor) and ((winding with slot) same stack\$3) | US-PGPUB; USPAT; IBM_TDB | OR | ON | 2005/10/27 08:06 |
| S43 | 1228 | (motor or stator or rotor) and ((winding with slot) same (stack or stacked or stacking)) | US-PGPUB; USPAT; IBM_TDB | OR | ON | 2005/10/27 08:07 |
| S44 | 695 | (motor or stator or rotor) and ((winding with slot) with (stack or stacked or stacking)) | US-PGPUB; USPAT; IBM_TDB | OR | ON | 2005/10/27 08:07 |
| S45 | 673 | (motor or rotor) and ((winding with slot) with (stack or stacked or stacking)) | US-PGPUB; USPAT; IBM_TDB | OR | ON | 2005/10/27 08:07 |
| S46 | 570 | (rotor) and ((winding with slot) with (stack or stacked or stacking)) | US-PGPUB; USPAT; IBM_TDB | OR | ON | 2005/10/27 08:08 |
| S47 | 303 | (rotor) same ((winding with slot) with (stack or stacked or stacking)) | US-PGPUB; USPAT; IBM_TDB | OR | ON | 2005/10/27 08:08 |
| S48 | 220 | (rotor) same ((winding with slot) with (stack or stacked or stacking)) and turn\$3 | US-PGPUB; USPAT; IBM_TDB | OR | ON | 2005/10/27 08:08 |
| S49 | 220 | (rotor) same ((winding with slot) with (stack or stacked or stacking)) and (turn or turned or turning) | US-PGPUB; USPAT; IBM_TDB | OR | ON | 2005/10/27 08:09 |

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| S50 | 44 | (rotor) same ((winding with slot) with (stack or stacked or stacking) with (turn or turned or turning)) | US-PGPUB; USPAT; IBM_TDB | OR | ON | 2005/10/27 12:18 |
| S51 | 8 | ("1799021" "2085099" "2333575" "5886434" "5986380").PN. | US-PGPUB; USPAT; USOCR | OR | ON | 2005/10/27 08:11 |
| S52 | 13 | ("5986380").URPN. | USPAT | OR | ON | 2005/10/27 08:24 |
| S53 | 1 | ("5162144").PN. | US-PGPUB; USPAT; IBM_TDB | OR | OFF | 2005/10/27 12:23 |
| S54 | 0 | ("(copperadjflash)withsputter\$3").PN. | US-PGPUB; USPAT; IBM_TDB | OR | OFF | 2005/10/27 12:24 |
| S55 | 4 | (copper adj flash) with sputter\$3 | US-PGPUB; USPAT; IBM_TDB | OR | ON | 2005/10/27 12:49 |
| S56 | 6373 | resistor and electrode and (dielectric or passivation) with (thick or thickness) | US-PGPUB; USPAT; IBM_TDB | OR | ON | 2005/10/27 12:51 |
| S57 | 2115 | resistor and electrode and (dielectric or passivation) near (thick or thickness) | US-PGPUB; USPAT; IBM_TDB | OR | ON | 2005/10/27 12:51 |
| S58 | 199 | resistor and electrode and (dielectric or passivation) near (thick or thickness) and electrode near (thick or thickness) | US-PGPUB; USPAT; IBM_TDB | OR | ON | 2005/10/27 12:53 |
| S60 | 119 | resistor and electrode and (dielectric or passivation) near (thick or thickness) and electrode near (thick or thickness) and micro\$5 | US-PGPUB; USPAT; IBM_TDB | OR | ON | 2005/10/27 12:58 |
| S61 | 106 | resistor and electrode and (dielectric or passivation) near (thick or thickness) and electrode near (thick or thickness) and (micro or micron or micrometer) | US-PGPUB; USPAT; IBM_TDB | OR | ON | 2005/10/27 13:00 |
| S62 | 106 | resistor and (dielectric or passivation) near (thick or thickness) and electrode near (thick or thickness) and (micro or micron or micrometer) | US-PGPUB; USPAT; IBM_TDB | OR | ON | 2005/10/27 13:03 |
| S63 | 91 | resistor and (dielectric or passivation) near (thick or thickness) and electrode near (thick or thickness) and (micron or micrometer) | US-PGPUB; USPAT; IBM_TDB | OR | ON | 2005/10/27 13:03 |